

# No1 EFEM TECHNOLOGY

## e-FRIEND 300

### 300 mm WAFER MINI-ENVIRONMENT SYSTEM

#### FEATURES

Available for 300 mm Wafer Application 25 Capacity FOUP

High Throughput 600 Wafer/h (Without ID Reading)

360 Wafer/h (With ID Reading)

Scalar Single Arm & Wafer Edge Clamp

Smooth Speed Control & Smart Motion

FOUP Interoperability

Small Footprint

SEMI Standard Compliant

#### SPECIFICATION

DIMENSION	1255(W) × 1150(D) × 1940(H)
LOADINGTIME	8 secs
P O W E R	220v or 110v(1ph, 50/60Hz)
M T B F	5,000 hours
M T T R	1 hour
CLEANLINES	Class 1( 0.1 μm )

#### OPTION

Wafer ID Reader
FOUP ID Reader
Wafer Mapping System
Opener Extention (Up to 4Set)
SECS - Interface
Parallel I/O Interface
PGV Interface
Cart Docking Interface

#### SEMI STANDARD

E15.1	300mm Tool Load Port.
E47.1	Boxes and Pods used to Transport and Store 300 mm Wafers.
E57	Kinematic Couplings.
E62	300mm Front-Opening Interface Mechanical Standards.
E63	300mm Bolts Interface.
E64	300mm Cart to E15.1 Docking Interface.
E23.1	PIO for AGV / PGV.



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